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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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Details

| | |
|----------------------------|---|
| Product Status | Active |
| Core Processor | dsPIC |
| Core Size | 16-Bit |
| Speed | 70 MIPS |
| Connectivity | I ² C, IrDA, LINbus, QEI, SPI, UART/USART |
| Peripherals | Brown-out Detect/Reset, DMA, I ² S, Motor Control PWM, POR, PWM, WDT |
| Number of I/O | 35 |
| Program Memory Size | 256KB (85.5K x 24) |
| Program Memory Type | FLASH |
| EEPROM Size | - |
| RAM Size | 32K x 8 |
| Voltage - Supply (Vcc/Vdd) | 3V ~ 3.6V |
| Data Converters | A/D 18x10b/12b |
| Oscillator Type | Internal |
| Operating Temperature | -40°C ~ 85°C (TA) |
| Mounting Type | Surface Mount |
| Package / Case | 44-TQFP |
| Supplier Device Package | 44-TQFP (10x10) |
| Purchase URL | https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256gm304-i-pt |

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

- Note 1:** This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the “dsPIC33/PIC24 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com)
- 2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXXGM3XX/6XX/7XX family requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **Section 2.2 “Decoupling Capacitors”**)
- All AVDD and AVSS pins (regardless if ADC module is not used) (see **Section 2.2 “Decoupling Capacitors”**)
- VCAP (see **Section 2.3 “CPU Logic Filter Capacitor Connection (VCAP)”**)
- MCLR pin (see **Section 2.4 “Master Clear (MCLR) Pin”**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 “ICSP Pins”**)
- OSC1 and OSC2 pins when external oscillator source is used (see **Section 2.6 “External Oscillator Pins”**)

Additionally, the following pins may be required:

- VREF+/VREF- pins are used when external voltage reference for ADC module is implemented

Note: The AVDD and AVSS pins must be connected independent of the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 μ F (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μ F to 0.001 μ F. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 μ F in parallel with 0.001 μ F.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

TABLE 4-16: QEI2 REGISTER MAP

| SFR Name | Addr. | Bit 15 | Bit 14 | Bit 13 | Bit 12 | Bit 11 | Bit 10 | Bit 9 | Bit 8 | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | All Resets |
|-----------|-------|----------------|--------|----------|----------|----------|----------|----------|----------|--------|---------|----------|----------|--------|--------|--------|--------|------------|
| QEI2CON | 05C0 | QEIEN | — | QEISIDL | PIMOD2 | PIMOD1 | PIMOD0 | IMV1 | IMV0 | — | INTDIV2 | INTDIV1 | INTDIV0 | CNTPOL | GATEN | CCM1 | CCM0 | 0000 |
| QEI2IOC | 05C2 | QCAPEN | FLTREN | QFDIV2 | QFDIV1 | QFDIV0 | OUTFNC1 | OUTFNC0 | SWPAB | HOMPOL | IDXPOL | QEBPOL | QEAPOL | HOME | INDEX | QEB | QEA | 000x |
| QEI2STAT | 05C4 | — | — | PCHEQIRQ | PCHEQIEN | PCLEQIRQ | PCLEQIEN | POSOVIRQ | POSOVIEN | PCIIRQ | PCIEN | VELOVIRQ | VELOVIEN | HOMIRQ | HOMIEN | IDXIRQ | IDXIEN | 0000 |
| POS2CNTL | 05C6 | POSCNT<15:0> | | | | | | | | | | | | | | | | 0000 |
| POS2CNTH | 05C8 | POSCNT<31:16> | | | | | | | | | | | | | | | | 0000 |
| POS2HLD | 05CA | POSHLD<15:0> | | | | | | | | | | | | | | | | 0000 |
| VEL2CNT | 05CC | VELCNT<15:0> | | | | | | | | | | | | | | | | 0000 |
| INT2TMRL | 05CE | INTTMR<15:0> | | | | | | | | | | | | | | | | 0000 |
| INT2TMRH | 05D0 | INTTMR<31:16> | | | | | | | | | | | | | | | | 0000 |
| INT2HLDL | 05D2 | INTHLD<15:0> | | | | | | | | | | | | | | | | 0000 |
| INT2HLDH | 05D4 | INTHLD<31:16> | | | | | | | | | | | | | | | | 0000 |
| INDX2CNTL | 05D6 | INDXCNT<15:0> | | | | | | | | | | | | | | | | 0000 |
| INDX2CNTH | 05D8 | INDXCNT<31:16> | | | | | | | | | | | | | | | | 0000 |
| INDX2HLD | 05DA | INDXHLD<15:0> | | | | | | | | | | | | | | | | 0000 |
| QEI2GECL | 05DC | QEIGEC<15:0> | | | | | | | | | | | | | | | | 0000 |
| QEI2ICL | 05DC | QEIIC<15:0> | | | | | | | | | | | | | | | | 0000 |
| QEI2GECH | 05DE | QEIGEC<31:16> | | | | | | | | | | | | | | | | 0000 |
| QEI2ICH | 05DE | QEIIC<31:16> | | | | | | | | | | | | | | | | 0000 |
| QEI2LECL | 05E0 | QEILEC<15:0> | | | | | | | | | | | | | | | | 0000 |
| QEI2LECH | 05E2 | QEILEC<31:16> | | | | | | | | | | | | | | | | 0000 |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-40: PMD REGISTER MAP FOR dsPIC33EPXXXGM3XX DEVICES

| SFR Name | Addr. | Bit 15 | Bit 14 | Bit 13 | Bit 12 | Bit 11 | Bit 10 | Bit 9 | Bit 8 | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | All Resets |
|----------|-------|--------|--------|--------|--------|--------|--------|-----------------------|--------|--------|-------|--------|--------|--------|--------|--------|--------|------------|
| PMD1 | 0760 | T5MD | T4MD | T3MD | T2MD | T1MD | QE11MD | PWMMD | DCIMD | I2C1MD | U2MD | U1MD | SPI2MD | SPI1MD | — | — | AD1MD | 0000 |
| PMD2 | 0762 | IC8MD | IC7MD | IC6MD | IC5MD | IC4MD | IC3MD | IC2MD | IC1MD | OC8MD | OC7MD | OC6MD | OC5MD | OC4MD | OC3MD | OC2MD | OC1MD | 0000 |
| PMD3 | 0764 | T9MD | T8MD | T7MD | T6MD | — | CMPMD | RTCCMD ⁽¹⁾ | PMPMD | CRCMD | — | QE12MD | — | U3MD | — | I2C2MD | ADC2MD | 0000 |
| PMD4 | 0766 | — | — | — | — | — | — | — | — | — | — | U4MD | — | REFOMD | CTMUMD | — | — | 0000 |
| PMD6 | 076A | — | — | PWM6MD | PWM5MD | PWM4MD | PWM3MD | PWM2MD | PWM1MD | — | — | — | — | — | — | — | SPI3MD | 0000 |
| PMD7 | 076C | — | — | — | — | — | — | — | — | — | — | — | DMA0MD | PTGMD | — | — | — | 0000 |
| | | | | | | | | | | | | | DMA1MD | | | | | |
| | | | | | | | | | | | | | DMA2MD | | | | | |
| | | | | | | | | | | | | | DMA3MD | | | | | |

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: The RTCCMD bit is not available on 44-pin devices.

TABLE 7-1: INTERRUPT VECTOR DETAILS (CONTINUED)

| Interrupt Source | Vector # | IRQ # | IVT Address | Interrupt Bit Location | | |
|--------------------------------|----------|---------|-------------------|------------------------|----------|--------------|
| | | | | Flag | Enable | Priority |
| SPI3E – SPI3 Error | 98 | 90 | 0x0000C8 | IFS5<10> | IEC5<10> | IPC22<10:8> |
| SPI3 – SPI3 Transfer Done | 99 | 91 | 0x0000CA | IFS5<11> | IEC5<11> | IPC22<14:12> |
| Reserved | 100-101 | 92-93 | 0x0000CC-0x0000CE | — | — | — |
| PWM1 – PWM Generator 1 | 102 | 94 | 0x0000D0 | IFS5<14> | IEC5<14> | IPC23<10:8> |
| PWM2 – PWM Generator 2 | 103 | 95 | 0x0000D2 | IFS5<15> | IEC5<15> | IPC23<14:12> |
| PWM3 – PWM Generator 3 | 104 | 96 | 0x0000D4 | IFS6<0> | IEC6<0> | IPC24<2:0> |
| PWM4 – PWM Generator 4 | 105 | 97 | 0x0000D6 | IFS6<1> | IEC6<1> | IPC24<6:4> |
| PWM5 – PWM Generator 5 | 106 | 98 | 0x0000D8 | IFS6<2> | IEC6<2> | IPC24<10:8> |
| PWM6 – PWM Generator 6 | 107 | 99 | 0x0000DA | IFS6<3> | IEC6<3> | IPC24<14:12> |
| Reserved | 108-149 | 100-141 | 0x0000DC-0x00012E | — | — | — |
| ICD – ICD Application | 150 | 142 | 0x000142 | IFS8<14> | IEC8<14> | IPC35<10:8> |
| JTAG – JTAG Programming | 151 | 143 | 0x000130 | IFS8<15> | IEC8<15> | IPC35<14:12> |
| Reserved | 152 | 144 | 0x000134 | — | — | — |
| PTGSTEP – PTG Step | 153 | 145 | 0x000136 | IFS9<1> | IEC9<1> | IPC36<6:4> |
| PTGWDT – PTG Watchdog Time-out | 154 | 146 | 0x000138 | IFS9<2> | IEC9<2> | IPC36<10:8> |
| PTG0 – PTG Interrupt 0 | 155 | 147 | 0x00013A | IFS9<3> | IEC9<3> | IPC36<14:12> |
| PTG1 – PTG Interrupt 1 | 156 | 148 | 0x00013C | IFS9<4> | IEC9<4> | IPC37<2:0> |
| PTG2 – PTG Interrupt 2 | 157 | 149 | 0x00013E | IFS9<5> | IEC9<5> | IPC37<6:4> |
| PTG3 – PTG Interrupt 3 | 158 | 150 | 0x000140 | IFS9<6> | IEC9<6> | IPC37<10:8> |
| Reserved | 159-245 | 151-245 | 0x000142-0x0001FE | — | — | — |
| Lowest Natural Order Priority | | | | | | |

Note 1: This interrupt source is available on dsPIC33EPXXXGM6XX/7XX devices only.

Note 2: This interrupt source is not available on 44-pin devices.

10.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGM3XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the “dsPIC33/PIC24 Family Reference Manual”, “Watchdog Timer and Power-Saving Modes” (DS70615), which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGM3XX/6XX/7XX devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

The dsPIC33EPXXXGM3XX/6XX/7XX devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV #IDLE_MODE     ; Put the device into Idle mode
```

10.1 Clock Frequency and Clock Switching

The dsPIC33EPXXXGM3XX/6XX/7XX devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 “Oscillator Configuration”**.

10.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXXGM3XX/6XX/7XX devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 10-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the Assembler Include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to “wake-up”.

10.3 Doze Mode

The preferred strategies for reducing power consumption are changing clock speed and invoking one of the power-saving modes. In some circumstances, this cannot be practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed can introduce communication errors, while using a power-saving mode can stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default setting.

Programs can use Doze mode to selectively reduce power consumption in event-driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption while the CPU Idles, waiting for something to invoke an interrupt routine. An automatic return to full-speed CPU operation on interrupts can be enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

For example, suppose the device is operating at 20 MIPS and the CAN module has been configured for 500 kbps based on this device operating speed. If the device is placed in Doze mode with a clock frequency ratio of 1:4, the CAN module continues to communicate at the required bit rate of 500 kbps, but the CPU now starts executing instructions at a frequency of 5 MIPS.

10.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled, using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

A peripheral module is enabled only if both the associated bit in the PMD register is cleared and the peripheral is supported by the specific dsPIC® DSC variant. If the peripheral is present in the device, it is enabled in the PMD register by default.

| |
|--|
| Note: If a PMD bit is set, the corresponding module is disabled after a delay of one instruction cycle. Similarly, if a PMD bit is cleared, the corresponding module is enabled after a delay of one instruction cycle (assuming the module control registers are already configured to enable module operation). |
|--|

dsPIC33EPXXXGM3XX/6XX/7XX

REGISTER 11-32: RPOR2: PERIPHERAL PIN SELECT OUTPUT REGISTER 2

| | | | | | | | |
|--------|-----|------------|-------|-------|-------|-------|-------|
| U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| — | — | RP39R<5:0> | | | | | |
| bit 15 | | | | | | | bit 8 |

| | | | | | | | |
|-------|-----|------------|-------|-------|-------|-------|-------|
| U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| — | — | RP38R<5:0> | | | | | |
| bit 7 | | | | | | | bit 0 |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP39R<5:0>:** Peripheral Output Function is Assigned to RP39 Output Pin bits
(see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP38R<5:0>:** Peripheral Output Function is Assigned to RP38 Output Pin bits
(see Table 11-3 for peripheral function numbers)

REGISTER 11-33: RPOR3: PERIPHERAL PIN SELECT OUTPUT REGISTER 3

| | | | | | | | |
|--------|-----|------------|-------|-------|-------|-------|-------|
| U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| — | — | RP41R<5:0> | | | | | |
| bit 15 | | | | | | | bit 8 |

| | | | | | | | |
|-------|-----|------------|-------|-------|-------|-------|-------|
| U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| — | — | RP40R<5:0> | | | | | |
| bit 7 | | | | | | | bit 0 |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP41R<5:0>:** Peripheral Output Function is Assigned to RP41 Output Pin bits
(see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP40R<5:0>:** Peripheral Output Function is Assigned to RP40 Output Pin bits
(see Table 11-3 for peripheral function numbers)

dsPIC33EPXXXGM3XX/6XX/7XX

13.1 Timer Control Registers

REGISTER 13-1: TxCON (T2CON, T4CON, T6CON AND T8CON) CONTROL REGISTER

| | | | | | | | |
|--------|-----|-------|-----|-----|-----|-----|-------|
| R/W-0 | U-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| TON | — | TSIDL | — | — | — | — | — |
| bit 15 | | | | | | | bit 8 |

| | | | | | | | |
|-------|-------|--------|--------|-------|-----|--------------------|-------|
| U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | U-0 | R/W-0 | U-0 |
| — | TGATE | TCKPS1 | TCKPS0 | T32 | — | TCS ⁽¹⁾ | — |
| bit 7 | | | | | | | bit 0 |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15 **TON:** Timerx On bit

When T32 = 1:

1 = Starts 32-bit Timerx/y

0 = Stops 32-bit Timerx/y

When T32 = 0:

1 = Starts 16-bit Timerx

0 = Stops 16-bit Timerx

bit 14 **Unimplemented:** Read as '0'

bit 13 **TSIDL:** Timerx Stop in Idle Mode bit

1 = Discontinues module operation when device enters Idle mode

0 = Continues module operation in Idle mode

bit 12-7 **Unimplemented:** Read as '0'

bit 6 **TGATE:** Timerx Gated Time Accumulation Enable bit

When TCS = 1:

This bit is ignored.

When TCS = 0:

1 = Gated time accumulation is enabled

0 = Gated time accumulation is disabled

bit 5-4 **TCKPS<1:0>:** Timerx Input Clock Prescale Select bits

11 = 1:256

10 = 1:64

01 = 1:8

00 = 1:1

bit 3 **T32:** 32-Bit Timer Mode Select bit

1 = Timerx and Timery form a single 32-bit timer

0 = Timerx and Timery act as two 16-bit timers

bit 2 **Unimplemented:** Read as '0'

bit 1 **TCS:** Timerx Clock Source Select bit⁽¹⁾

1 = External clock is from pin, TxCK (on the rising edge)

0 = Internal clock (Fp)

bit 0 **Unimplemented:** Read as '0'

Note 1: The TxCK pin is not available on all timers. Refer to the “Pin Diagrams” section for the available pins.

FIGURE 16-2: HIGH-SPEED PWMx MODULE REGISTER INTERCONNECTION DIAGRAM

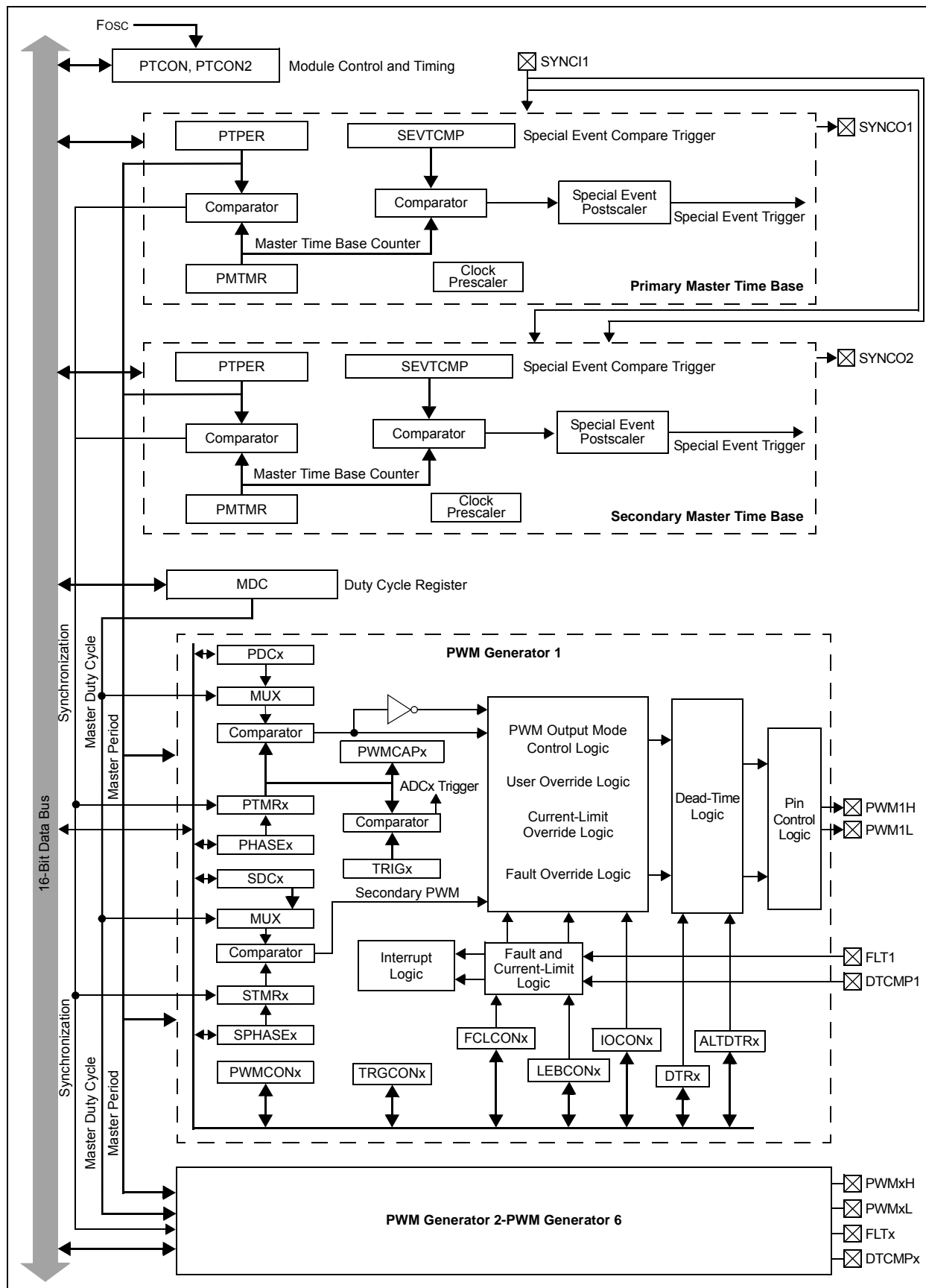
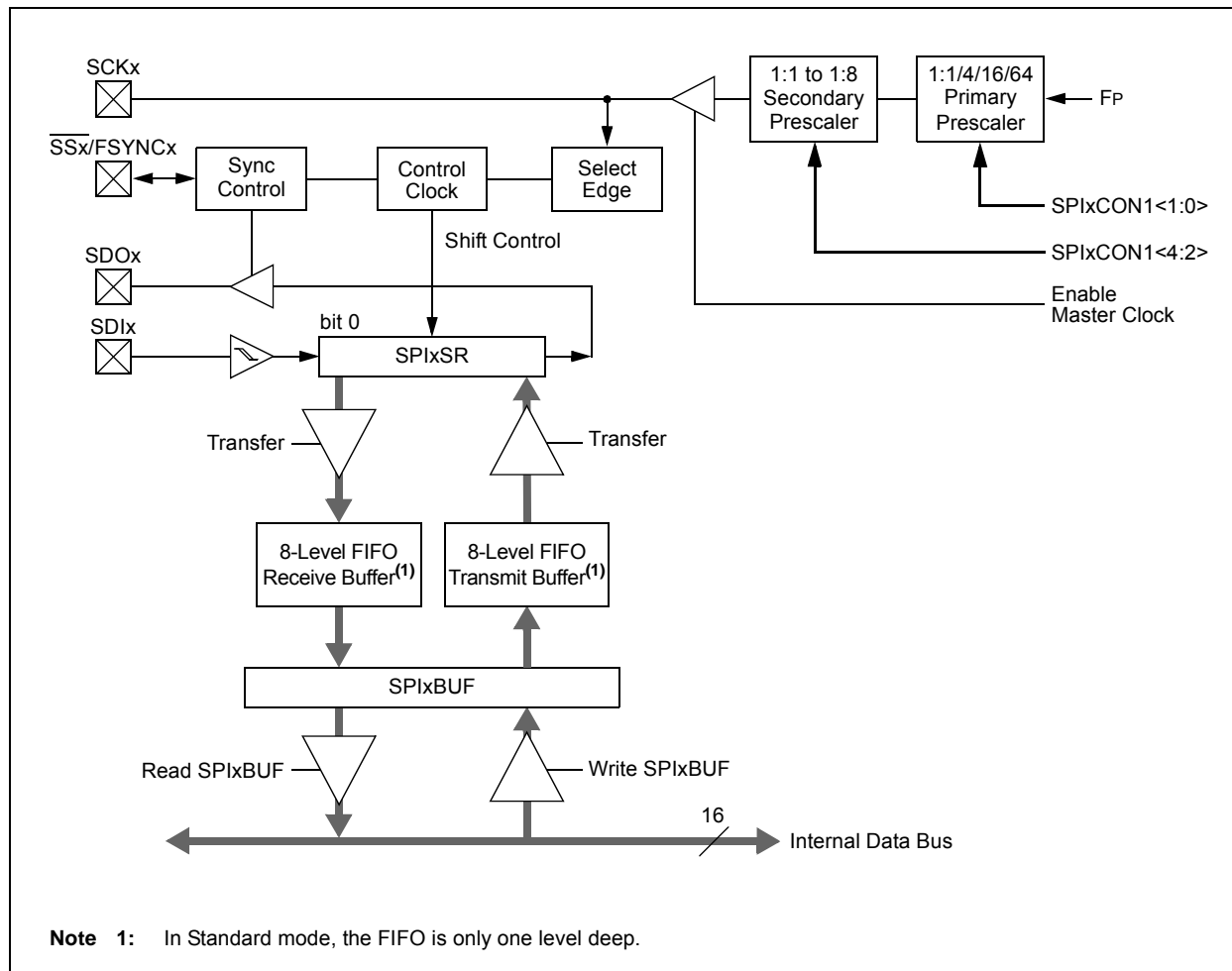


FIGURE 18-1: SPIx MODULE BLOCK DIAGRAM



REGISTER 19-2: I2CxSTAT: I2Cx STATUS REGISTER

| | | | | | | | |
|----------|----------|-----|-----|-----|-----------|----------|----------|
| R-0, HSC | R-0, HSC | U-0 | U-0 | U-0 | R/C-0, HS | R-0, HSC | R-0, HSC |
| ACKSTAT | TRSTAT | — | — | — | BCL | GCSTAT | ADD10 |
| bit 15 | | | | | | bit 8 | |

| | | | | | | | |
|-----------|-----------|----------|------------|------------|----------|----------|----------|
| R/C-0, HS | R/C-0, HS | R-0, HSC | R/C-0, HSC | R/C-0, HSC | R-0, HSC | R-0, HSC | R-0, HSC |
| IWCOL | I2COV | D_A | P | S | R_W | RBF | TBF |
| bit 7 | | | | | | bit 0 | |

| | | |
|-------------------|-------------------|---|
| Legend: | C = Clearable bit | U = Unimplemented bit, read as '0' |
| R = Readable bit | W = Writable bit | HS = Hardware Settable bit HSC = Hardware Settable/Clearable bit |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared x = Bit is unknown |

- bit 15 **ACKSTAT:** Acknowledge Status bit
(when operating as I²C™ master, applicable to master transmit operation)
1 = NACK received from slave
0 = ACK received from slave
Hardware sets or clears at the end of a slave Acknowledge.
- bit 14 **TRSTAT:** Transmit Status bit (when operating as I²C master, applicable to master transmit operation)
1 = Master transmit is in progress (8 bits + ACK)
0 = Master transmit is not in progress
Hardware sets at the beginning of a master transmission. Hardware clears at the end of a slave Acknowledge.
- bit 13-11 **Unimplemented:** Read as '0'
- bit 10 **BCL:** Master Bus Collision Detect bit
1 = A bus collision has been detected during a master operation
0 = No collision
Hardware sets at detection of a bus collision.
- bit 9 **GCSTAT:** General Call Status bit
1 = General call address was received
0 = General call address was not received
Hardware sets when address matches the general call address. Hardware clears at Stop detection.
- bit 8 **ADD10:** 10-Bit Address Status bit
1 = 10-bit address was matched
0 = 10-bit address was not matched
Hardware sets at a match of the 2nd byte of a matched 10-bit address. Hardware clears at Stop detection.
- bit 7 **IWCOL:** I2Cx Write Collision Detect bit
1 = An attempt to write to the I2CxTRN register failed because the I²C module is busy
0 = No collision
Hardware sets at an occurrence of a write to I2CxTRN while busy (cleared by software).
- bit 6 **I2COV:** I2Cx Receive Overflow Flag bit
1 = A byte was received while the I2CxRCV register was still holding the previous byte
0 = No overflow
Hardware sets at an attempt to transfer I2CxRSR to I2CxRCV (cleared by software).
- bit 5 **D_A:** Data/Address bit (when operating as I²C slave)
1 = Indicates that the last byte received was data
0 = Indicates that the last byte received was a device address
Hardware clears at a device address match. Hardware sets by reception of a slave byte.
- bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware sets or clears when Start, Repeated Start or Stop is detected.

REGISTER 21-5: CxFIFO: CANx FIFO STATUS REGISTER

| | | | | | | | |
|--------|-----|------|------|------|------|------|-------|
| U-0 | U-0 | R-0 | R-0 | R-0 | R-0 | R-0 | R-0 |
| — | — | FBP5 | FBP4 | FBP3 | FBP2 | FBP1 | FBP0 |
| bit 15 | | | | | | | bit 8 |

| | | | | | | | |
|-------|-----|-------|-------|-------|-------|-------|-------|
| U-0 | U-0 | R-0 | R-0 | R-0 | R-0 | R-0 | R-0 |
| — | — | FNRB5 | FNRB4 | FNRB3 | FNRB2 | FNRB1 | FNRB0 |
| bit 7 | | | | | | | bit 0 |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **FBP<5:0>:** FIFO Buffer Pointer bits

011111 = RB31 buffer

011110 = RB30 buffer

•

•

•

000001 = TRB1 buffer

000000 = TRB0 buffer

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **FNRB<5:0>:** FIFO Next Read Buffer Pointer bits

011111 = RB31 buffer

011110 = RB30 buffer

•

•

•

000001 = TRB1 buffer

000000 = TRB0 buffer

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REGISTER 24-5: RSCON: DCI RECEIVE SLOT CONTROL REGISTER

| | | | | | | | |
|-----------|-------|-------|-------|-------|-------|-------|-------|
| R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| RSE<15:8> | | | | | | | |
| bit 15 | | | | bit 8 | | | |

| | | | | | | | |
|----------|-------|-------|-------|-------|-------|-------|-------|
| R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| RSE<7:0> | | | | | | | |
| bit 7 | | | | bit 0 | | | |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 15-0

RSE<15:0>: DCI Receive Slot Enable bits

1 = CSDI data is received during Individual Time Slot n

0 = CSDI data is ignored during Individual Time Slot n

REGISTER 24-6: TSCON: DCI TRANSMIT SLOT CONTROL REGISTER

| | | | | | | | |
|-----------|-------|-------|-------|-------|-------|-------|-------|
| R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| TSE<15:8> | | | | | | | |
| bit 15 | | | | bit 8 | | | |

| | | | | | | | |
|----------|-------|-------|-------|-------|-------|-------|-------|
| R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| TSE<7:0> | | | | | | | |
| bit 7 | | | | bit 0 | | | |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

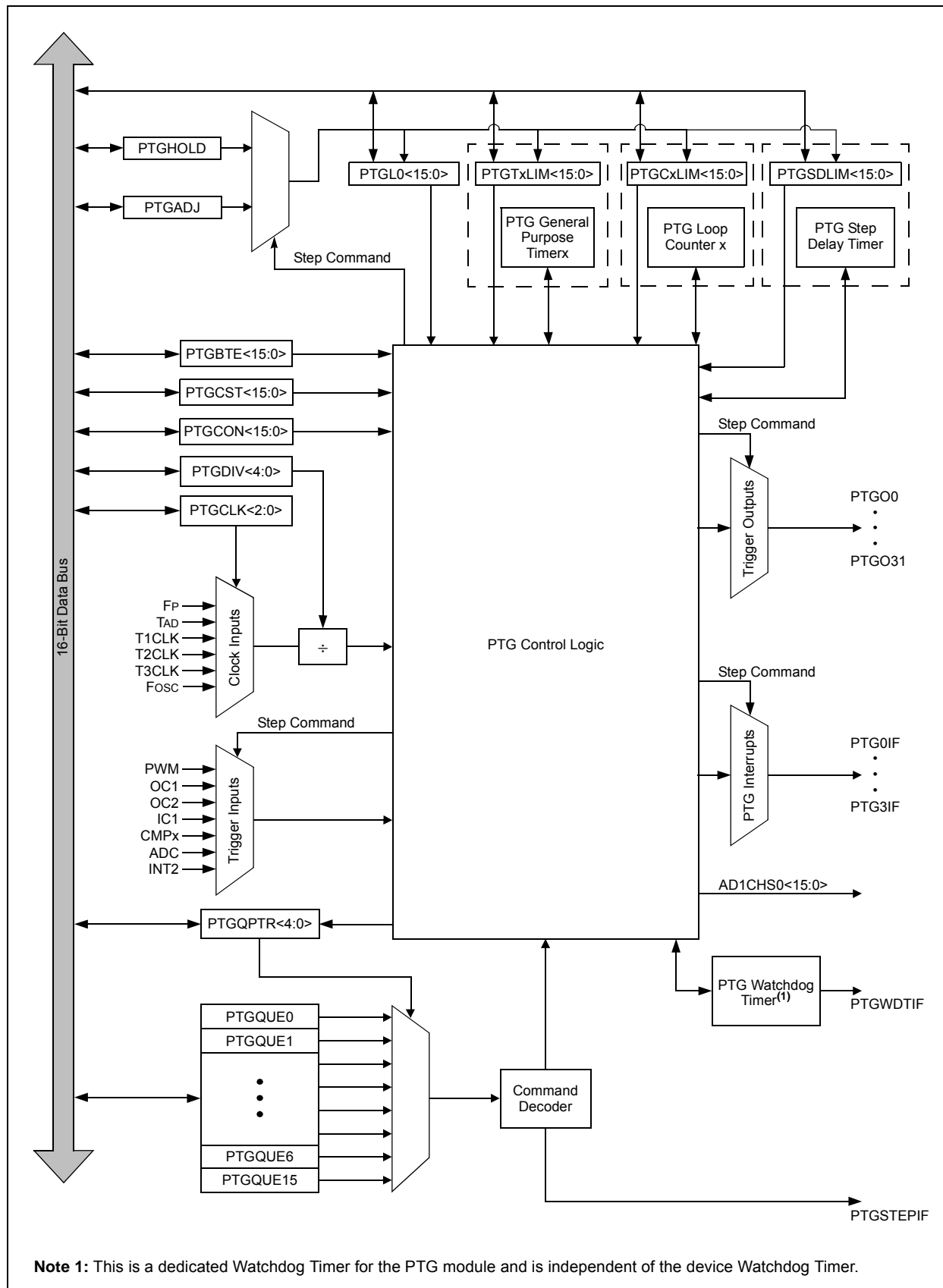
bit 15-0

TSE<15:0>: DCI Transmit Slot Enable Control bits

1 = Transmit buffer contents are sent during Individual Time Slot n

0 = CSDO pin is tri-stated or driven to logic '0' during the individual time slot, depending on the state of the CSDOM bit

FIGURE 25-1: PTG BLOCK DIAGRAM



27.1 Writing to the RTCC Timer

Note: To allow the RTCC module to be clocked by the secondary crystal oscillator, the Secondary Oscillator Enable (LPOSCEN) bit in the Oscillator Control (OSCCON<1>) register must be set. For further details, refer to the “dsPIC33/PIC24 Family Reference Manual”, “Oscillator” (DS70580).

The user application can configure the time and calendar by writing the desired seconds, minutes, hours, weekday, date, month and year to the RTCC registers. Under normal operation, writes to the RTCC Timer registers are not allowed. Attempted writes will appear to execute normally, but the contents of the registers will remain unchanged. To write to the RTCC register, the RTCWREN bit (RCFGCAL<13>) must be set. Setting the RTCWREN bit allows writes to the RTCC registers. Conversely, clearing the RTCWREN bit prevents writes.

To set the RTCWREN bit, the following procedure must be executed. The RTCWREN bit can be cleared at any time:

1. Write 0x55 to NVMKEY.
2. Write 0xAA to NVMKEY.
3. Set the RTCWREN bit using a single-cycle instruction.

The RTCC module is enabled by setting the RTCEN bit (RCFGCAL<15>). To set or clear the RTCEN bit, the RTCWREN bit (RCFGCAL<13>) must be set.

If the entire clock (hours, minutes and seconds) needs to be corrected, it is recommended that the RTCC module should be disabled to avoid coincidental write operation when the timer increments. Therefore, it stops the clock from counting while writing to the RTCC Timer register.

27.2 RTCC Resources

Many useful resources related to RTCC are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note: In the event you are not able to access the product page using the link above, enter this URL in your browser:
<http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en554310>

27.2.1 KEY RESOURCES

- “Real-Time Clock and Calendar (RTCC)” (DS70584) in the “dsPIC33/PIC24 Family Reference Manual”
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related “dsPIC33/PIC24 Family Reference Manual” Sections
- Development Tools

30.5 Watchdog Timer (WDT)

For dsPIC33EPXXXGM3XX/6XX/7XX devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

30.5.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a WDT time-out period (TWDT), as shown in Parameter SY12 in Table 33-21.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>), which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDI instruction during normal execution

Note: The CLRWDI and PWRSAV instructions clear the prescaler and postscaler counts when executed.

30.5.2 SLEEP AND IDLE MODES

If the WDT is enabled, it continues to run during Sleep or Idle modes. When the WDT time-out occurs, the device wakes the device and code execution continues from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bit (RCON<3,2>) needs to be cleared in software after the device wakes up.

30.5.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDI Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

30.5.4 WDT WINDOW

The Watchdog Timer has an optional Windowed mode enabled by programming the WINDIS bit in the WDT Configuration register (FWDI<6>). In the Windowed mode (WINDIS = 0), the WDT should be cleared based on the settings in the programmable Watchdog Timer Window select bits (WDTWIN<1:0>).

FIGURE 30-2: WDT BLOCK DIAGRAM

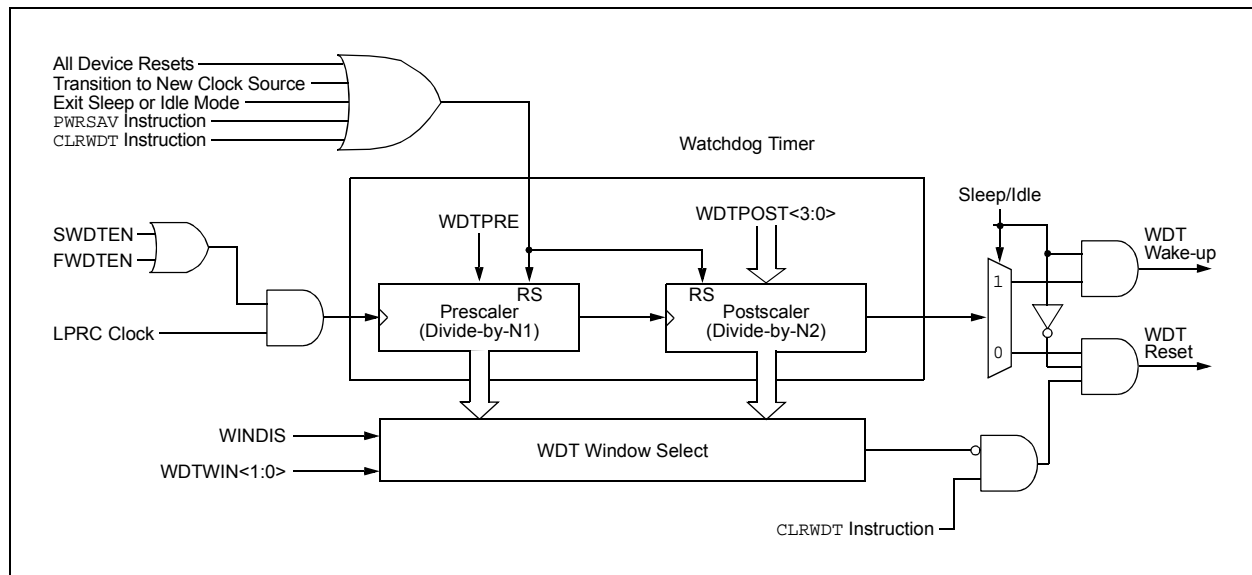


TABLE 33-7: DC CHARACTERISTICS: IDLE CURRENT (IDLE)

| DC CHARACTERISTICS | | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended | | | |
|------------------------------------|---------------------|------|--|------------|------|---------|
| Parameter No. | Typ. ⁽²⁾ | Max. | Units | Conditions | | |
| Idle Current (IDLE) ⁽¹⁾ | | | | | | |
| DC40d | 1.5 | 8.0 | mA | -40°C | 3.3V | 10 MIPS |
| DC40a | 1.5 | 8.0 | mA | +25°C | | |
| DC40b | 1.5 | 8.0 | mA | +85°C | | |
| DC40c | 1.5 | 8.0 | mA | +125°C | | |
| DC41d | 2.0 | 12.0 | mA | -40°C | 3.3V | 20 MIPS |
| DC41a | 2.0 | 12.0 | mA | +25°C | | |
| DC41b | 2.0 | 12.0 | mA | +85°C | | |
| DC41c | 2.0 | 12.0 | mA | +125°C | | |
| DC42d | 5.5 | 15.0 | mA | -40°C | 3.3V | 40 MIPS |
| DC42a | 5.5 | 15.0 | mA | +25°C | | |
| DC42b | 5.5 | 15.0 | mA | +85°C | | |
| DC42c | 5.5 | 15.0 | mA | +125°C | | |
| DC43d | 9.0 | 20.0 | mA | -40°C | 3.3V | 60 MIPS |
| DC43a | 9.0 | 20.0 | mA | +25°C | | |
| DC43b | 9.0 | 20.0 | mA | +85°C | | |
| DC43c | 9.0 | 20.0 | mA | +125°C | | |
| DC44d | 10.0 | 25.0 | mA | -40°C | 3.3V | 70 MIPS |
| DC44a | 10.0 | 25.0 | mA | +25°C | | |
| DC44b | 10.0 | 25.0 | mA | +85°C | | |

Note 1: Base Idle current (IDLE) is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as outputs and driving low
- MCLR = VDD, WDT and FSCM are disabled
- No peripheral modules are operating or being clocked (defined PMDx bits are all ones)
- The NVMSIDL bit (NVMCON<12>) = 1 (i.e., Flash regulator is set to standby while the device is in Idle mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

2: Data in the "Typical" column is at 3.3V, +25°C unless otherwise specified.

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TABLE 34-11: PLL CLOCK TIMING SPECIFICATIONS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$ | | | | |
|--------------------|--------|--|---|-----|-----|-------|-----------------------------|
| Param No. | Symbol | Characteristic | Min | Typ | Max | Units | Conditions |
| HOS53 | DCLK | CLKO Stability (Jitter) ⁽¹⁾ | -5 | 0.5 | 5 | % | Measured over 100 ms period |

Note 1: These parameters are characterized by similarity, but are not tested in manufacturing. This specification is based on clock cycle by clock cycle measurements. To calculate the effective jitter for individual time bases or communication clocks use this formula:

$$\text{Peripheral Clock Jitter} = \frac{DCLK}{\sqrt{\left(\frac{FOSC}{\text{Peripheral Bit Rate Clock}}\right)}}$$

For example: FOSC = 32 MHz, DCLK = 5%, SPIx bit rate clock (i.e., SCKx) is 2 MHz.

$$\text{SPI SCK Jitter} = \left[\frac{DCLK}{\sqrt{\left(\frac{32 \text{ MHz}}{2 \text{ MHz}}\right)}} \right] = \left[\frac{5\%}{\sqrt{16}} \right] = \left[\frac{5\%}{4} \right] = 1.25\%$$

TABLE 34-12: INTERNAL FRC ACCURACY

| AC CHARACTERISTICS | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$ | | | | | |
|--------------------|--|---|-----|-----|-------|--|----------------|
| Param No. | Characteristic | Min | Typ | Max | Units | Conditions | |
| HF20 | Internal FRC Accuracy @ FRC Frequency = 7.3728 MHz | | | | | | |
| | FRC | -3 | — | +3 | % | $-40^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$ | VDD = 3.0-3.6V |

TABLE 34-13: INTERNAL RC ACCURACY

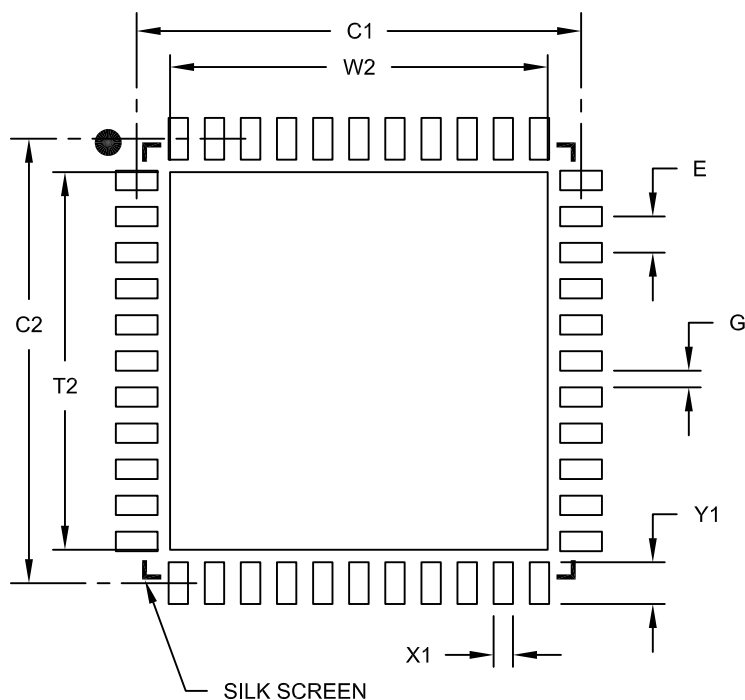
| AC CHARACTERISTICS | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$ | | | | | |
|--------------------|------------------------------------|---|-----|-----|-------|--|----------------|
| Param No. | Characteristic | Min | Typ | Max | Units | Conditions | |
| HF21 | LPRC @ 32.768 kHz ^(1,2) | | | | | | |
| | LPRC | -30 | — | +30 | % | $-40^{\circ}\text{C} \leq T_A \leq +150^{\circ}\text{C}$ | VDD = 3.0-3.6V |

Note 1: Change of LPRC frequency as VDD changes.

Note 2: LPRC accuracy impacts the Watchdog Timer Time-out Period (TWDT1). See **Section 30.5 “Watchdog Timer (WDT)”** for more information.

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Units | | MILLIMETERS | | |
|----------------------------|----|-------------|------|------|
| Dimension Limits | | MIN | NOM | MAX |
| Contact Pitch | E | 0.65 BSC | | |
| Optional Center Pad Width | W2 | | | 6.60 |
| Optional Center Pad Length | T2 | | | 6.60 |
| Contact Pad Spacing | C1 | | 8.00 | |
| Contact Pad Spacing | C2 | | 8.00 | |
| Contact Pad Width (X44) | X1 | | | 0.35 |
| Contact Pad Length (X44) | Y1 | | | 0.85 |
| Distance Between Pads | G | 0.25 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B

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